

Features

1. Surface Mounted Devices with a small dimension of 3.6 x 1.6 x 1.2 mm³ meet future miniaturization trend.

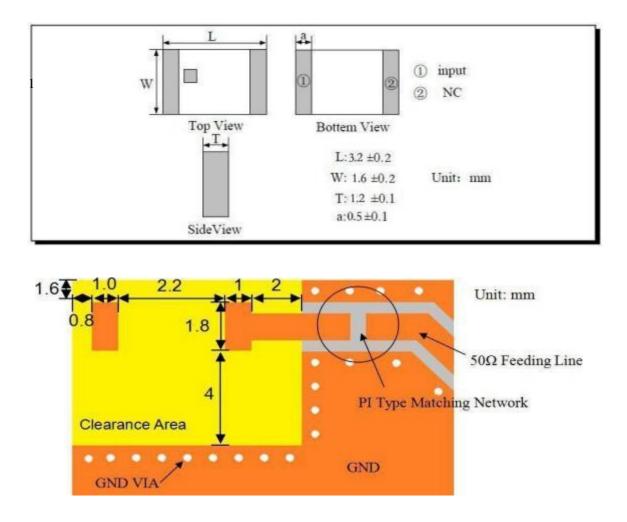
2.Embedded and LTCC (Low Temperature Co-fired Ceramic) technology is able to future integratewith system design as well as beautifying the housing of final product.

3. High Stability in Temperature / Humidity Change

Applications

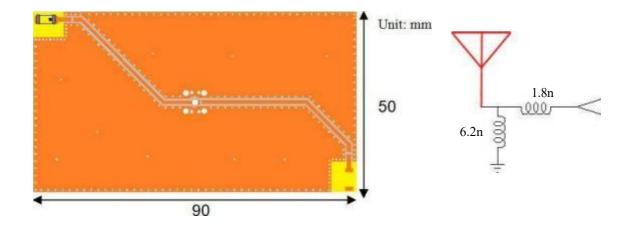
- 1. Bluetooth
- 2. Wireless LAN
- 3. HormRF
- 4. ISMband 2.4GHz wireless applications

Dimensions (Unit: mm)





Evaluation Board and Matching Circuits



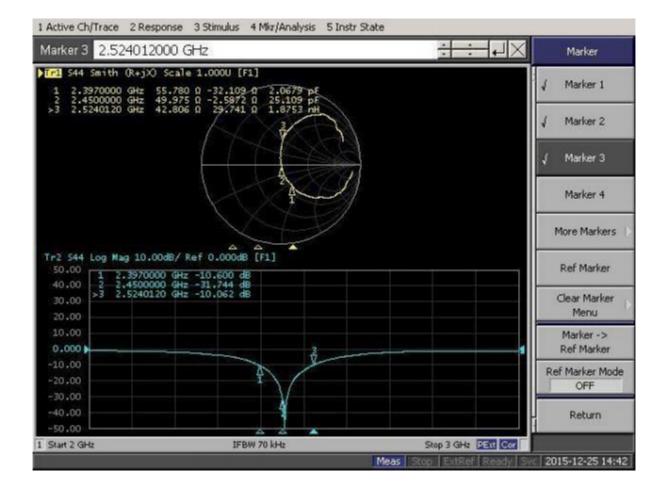
Electrical Characteristics

| No. | Item | Specifications |
|-----|---------------------------------|------------------|
| 1 | Central Frequency (No matching) | 2875MHz |
| | After Matching | 2450 MHz |
| 2 | BandWidth | 100MHz typ. |
| 3 | Peak Gain | 5.19 dBi |
| 4 | V.S.W.R | ≤2.0 |
| 5 | Polarization | Linear |
| 6 | Azimuth Beam width | Omni-directional |
| 7 | Impedance | 50 Ω |



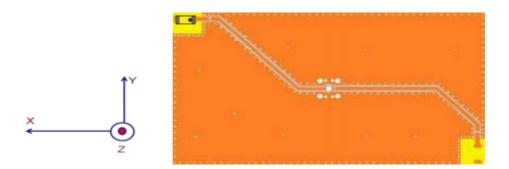
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Characteristic curve



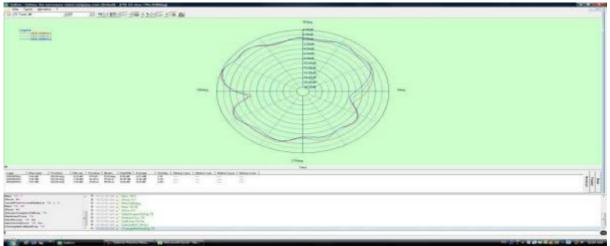
Radiation Pattern

coordinates:

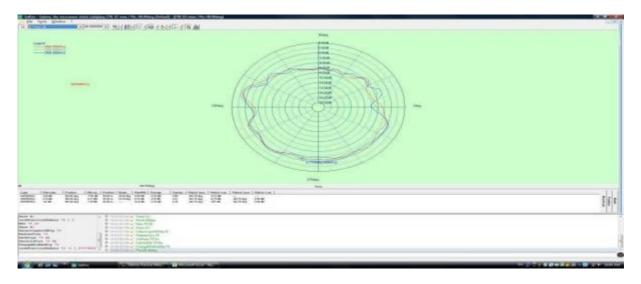




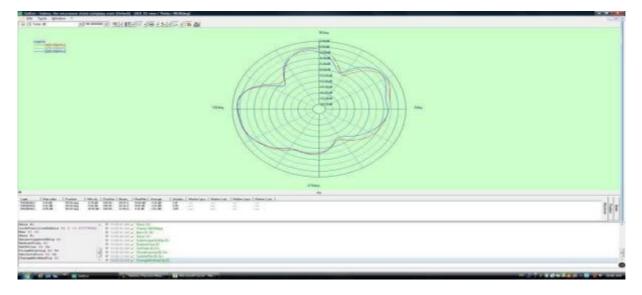
X-Z Plane



Y-Z Plane

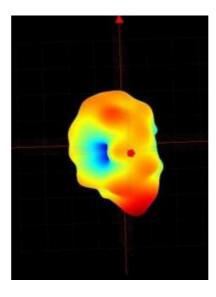


X-Y Plane





3D Radiation Pattern



| Frequency (MHz) | 2400 | 2450 | 2500 |
|--------------------|-------|-------|-------|
| Avg. Gain (dBi) | -0.23 | -0.36 | -0.51 |
| Peck Gain (dBi) | 4.98 | 5.19 | 4.55 |
| Efficiency (%) | 70 | 71.2 | 69 |



Post Dependability Tolerance

Post Dependability Tolerance (Refer to the table)

| No. | Item | Post Dependability Tolerance |
|-----|-------------------|------------------------------|
| 1 | Central Frequency | ±5 MHz |
| 2 | BandWidth | ±5 MHz |
| 3 | Gain | ±0.1 dBi |
| 4 | V.S.W.R (in BW) | ±0.1 |

Dependability Test

| Temperature range Relative | 25±5°C |
|-----------------------------|-------------|
| Humidity range | 55~75%RH |
| Operating Temperature range | -40°C~+85°C |

Vibration Resist

The device should satisfy the electrical characteristics specified in paragraph $1 \sim 4$ after applied to the vibration of 10 to 55Hz with amplitude of 1.5mm for 2 hours each in X , Y and Z directions.

Drop Shock

The device should satisfy the electrical characteristics specified in paragraph $1 \sim 4$ after dropping onto the hard wooden board from the height of 100cm for 3 times each facet of the 3 dimensions of the device.

Solder Heat Proof

The device should be satisfied after preheating at 120 $^{\circ}$ C ~ 150 $^{\circ}$ C for 120 seconds and dipping in soldering Sn at 255 $^{\circ}$ C+10 $^{\circ}$ C for 5 ± 0.5 seconds, or electric iron 300 $^{\circ}$ C-10 $^{\circ}$ C for 3 ± 0.5 seconds, without damnify.

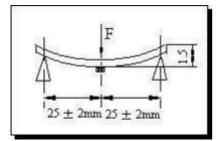
Adhesive Strength of Termination

The device have no remarkable damage or removal of the termination after horizontal force of $5N (\leq 0603)$; 10N (> 0603) with 10 ± 1 seconds.



HYX321612A07

Bending Resist Test



Weld the product to the center part of the PCB with the thickness 1.6 ± 0.2 mm as the illustration shows, and keep exerting force arrowward on it at speed of :1mm/S , and hold for 5 ± 1 S at the position of 1.5mm bending distance , so far , any peeling off of the product metal coating should not be detected

Moisture Proof

The device should satisfy the electrical characteristics specified in paragraph 8.1~8.4 after exposed to the temperature 60 ± 2 °C and the relative humidity 90~95% RH for 96 hours and 1~2 hours recovery time under normal condition.

High Temperature Endurance

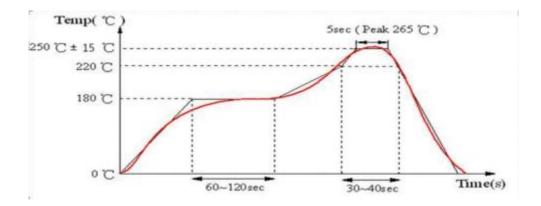
The device should satisfy the electrical characteristics specified in paragraph 8.1~8.4 after exposed to temperature 85 ± 5 °C for 96±2 hours and 1~2 hours recovery time under normal temperature.

Low Temperature Endurance

The device should also satisfy the electrical characteristics specified in paragraph 8. 1~8.4 after exposed to the temperature -40 °C \pm 5 °C for 96 \pm 2 hours and to 2 hours recovery time under normal temperature.

Temperature Cycle Test

The device should also satisfy the electrical characteristics specified in paragraph 8.1~8.4 after exposed to the low temperature -40 °C and high temperature +85 °C for 30 ± 2 min each by 5 cycles and 1 to 2 hours recovery time under normal temperature.

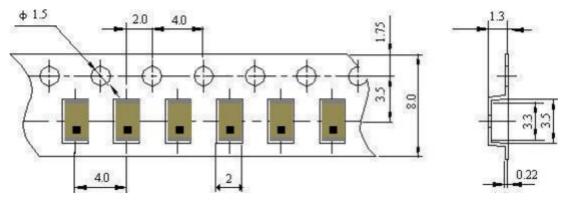


Reflow Soldering Standard Condition



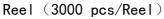
Packaging and Dimensions (3216)

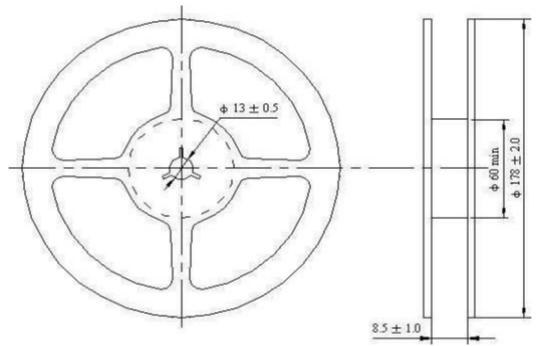
Plastic Tape



Remarks for Package

Reserve a length of 150~200mm for the trailer of the carrier and 250~300 mm for the leader of the carrier and further 250mm of cover tape at the leading part of the carrier.





Storage Period

Product should be used within six months of receipt. MSL 1 / Storage Temperature Range : <30 degree C, Humidity : <85%RH